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Case Docket No. ABE-034 U.S. DEPARTMENT OF COMMERCE Patent and Trademark Office $1-9-06$ RECORDATION FORM COVER SHEET PATENTS ONLY				
To the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof.				
1. Name of conveying parties:				
Eiji KAMIYAMA and Takeo KATOH				
Additional name(s) of conveying party(ies) attached? Yes No _XX_				
2. Name and address of receiving party:				
Name: Sumco Corporation				
Internal Address:				
Street Address: 2-1, Shibaura 1-chome, Minato-ku, Tokyo 105-8634, Japan				
Additional name(s) & address(es) attached? Yes No XX_				
3. Nature of conveyance:				
XX Assignment Merger				
Security Agreement Change of Name				
Other:				
Execution Date: September 16 and September 20, 2005, respectively				
4. Title: BONDED SEMICONDUCTOR SUBSTRATE AND MANUFACTURING METHOD THEREOF				
5. Application number(s) or patent number(s):				
If this document is being filed together with a new application, the execution date of the application is:				
A. Patent Application No.(s) B. Patent No.(s)				
10/550,761				
Anditional numbers attached? Yes No yy				

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PATENT REEL: 017828 FRAME: 0982

Case Docket No. ABE-034	U.S. DEPARTMENT OF COMMERCE Patent and Trademark Office			
RECORDATION FORM COVER SHEET  PATENTS ONLY				
6. Name and address of party to whom corresponding Suite 710	pondence concerning document			
900 17th Street, N.W. Washington, D.C. 20006	1			
7. Total number of applications and patents in	nvolved: 1			
8. Total fee (37 CFR 3.41)	\$ <u>40.00</u>			
XX Authorized to be charged by credit card				
Check enclosed				
Authorized to be charged to Deposit Account				
9. Deposit Account No.: <u>111833</u>				
10. In the event any additional fees are required, please charge our Deposit Account No.: <u>111833</u> .				
11. Statement and signature.				
To the best of my knowledge and belief, to true and correct and any attached copy is document.				
Keiko Tanaka Kubovcik Name of Person Signing Signature	<u>January 9, 2006</u> Date			
<u>40,428</u> Registration Nu	ımber			
Total number of pages, including cover sheet, attachments, and document:	3			
Atty. Docket No. ABE-034				
KTK/3hf	ľ			

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**RECORDED: 01/09/2006** 

## **U.S. ASSIGNMENT**

	IN CONSIDERATION of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter ASSIGNOR) by			
Insert ASSIGNEE'S Iame(s) Address(es))	Dunio Corporation			
	(hereinafter ASSIGNEE), the receipt of which is hereby acknowledged, the undersigned ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE the entire and exclusive right, title and interest to the invention entitled			
Title of Invention)	Bonded semiconductor substrate and manufacturing method thereof			
If the assignment is eing filed after the	for which application for Letters Patent of the United States was executed on even date herewith unless otherwise indicated below:			
ling of the pplication, this section nust be completed)	*filed on, Serial No, Serial No (Kubovcik & Kubovcik is hereby authorized to insert the series code, serial number and/or filing date, when known)			
	and to all Letters Patent of the United States to be obtained thereof on said application or any continuation, divisional, substitute, reissue or reexamination thereof for the full term or terms for which the same may be granted.			
	The ASSIGNOR agrees to execute all papers necessary in connection with this application and any continuing, divisional, reissue or reexamination applications thereof and also to execute separate assignments in connection with such applications as the ASSIGNEE may deem necessary or expedient.			
	interference, litigation, or application or any continuation reissue patent issued thereof	es to execute all papers necestother legal proceeding which maion, divisional, reissue or reexaming and to cooperate with the ASSI idence and proceeding with such	ay be declared concerning this ation thereof or Letters Patent or GNEE in every way possible in	
ignatures)	IN WITNESS WHEREOF, the undersigned inventor(s) has (have) affixed his/her/their signature(s).			
	Eiji Kamiyama (SIGNATURE)	Eiji Kamiyama	16/9/2005 (DATE)	
	(SIGNATURE)  Jaker Hand	(TYPE NAME) Takco Katoh	(DATE) 20/9/2005	
	(SIGNATURE)	(TYPE NAME)	(DATE)	
	(SIGNATURE)	(TYPE NAME)	(DATE)	
	(SIGNATURE)	(TYPE NAME)	(DATE)	
	(SIGNATURE)	(TYPE NAME)	(DATE)	
	NO LEGALIZATION REQU	JIRED		

08/00